

ABSTRACT OF THE DISCLOSURE

Plasma reaction by products are removed from ceramic parts of semiconductor fabrication equipment by dipping the ceramic parts into a cleaning solution, rinsing the ceramic parts, and treating the ceramic parts with heat. The cleaning ~~Cleaning solution is used to clean ceramic parts using the same. The cleaning~~ solution includes about 5-30% by weight of fluoric salt, about 10-20% by weight of organic acid, about 30-50% by weight of organic solvent, and about ~~50%~~ 20-50% by weight of water. The ceramic parts may be portions of an etching apparatus on which plasma reaction by-products are adsorbed. ~~Plasma reaction by products are removed from the ceramic parts dipping the parts into the cleaning solution, followed by rinsing and heat treatment.~~

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Plasma reaction by-products are removed from ceramic parts of semiconductor fabrication equipment by dipping the ceramic parts into a cleaning solution, rinsing the ceramic parts, and treating the ceramic parts with heat. The cleaning solution includes about 5-30% by weight of fluoric salt, about 10-20% by weight of organic acid, about 30-50% by weight of organic solvent, and about 20-50% by weight of water. The ceramic parts may be portions of an etching apparatus on which plasma reaction by-products are adsorbed.